

100W - 28V - 1GHz
GOLD METALIZED MULTI-PURPOSE
SILICON DMOS RF FET

FEATURES

- METAL GATE
- EXTRA LOW C_{rss}
- BROAD BAND
- SIMPLE BIAS CIRCUITS
- LOW NOISE
- HIGH GAIN

APPLICATIONS

- HF/VHF/UHF COMMUNICATIONS
from DC to 1GHz

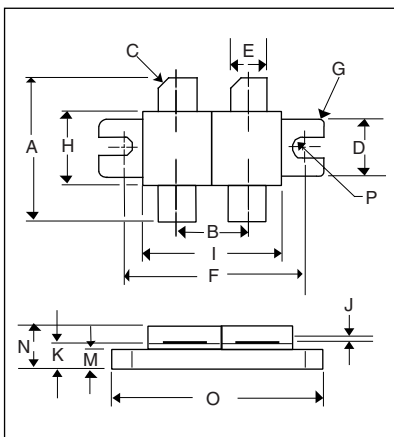
ABSOLUTE MAXIMUM RATINGS
($T_{CASE} = 25^{\circ}C$ unless otherwise stated)

P_D	Power Dissipation	293W
BV_{DSS}	Drain-source breakdown voltage	65V
V_{GS}	Gate-source voltage	$\pm 20V$
I_D	Drain Current	32A
T_{stg}	Storage temperature	-65 to 150°C
T_j	Maximum operating junction temperature	200°C
$R_{THj-case}$	Thermal resistance junction-case	Max. 0.6°C/W

ELECTRICAL CHARACTERISTICS ($T_{CASE} = 25^{\circ}C$ unless otherwise stated)

Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<u>PER SIDE</u>					
BV_{DSS}	Breakdown voltage, drain sourc $V_{GS}=0$ $I_D=100mA$	65			Vdc
I_{DSS}	Drain leakage current $V_{DS}=28V$ $V_{GS}=0$			4	mAdc
I_{GSS}	Gate leakage current $V_{GS}=20V$ $V_{DS}=0$			1	μ Adc
$V_{GS(th)}$	Gate threshold voltage $I_D=10mA$ $V_{DS}=V_{GS}$	1		7	Vdc
g_{fs}	Transconductance (300 μ s pulse) $V_{DS}=10V$ $I_D=3.2A$	3.2			Mhos
<u>TOTAL DEVICE</u>					
G_{ps}	Common source power gain $P_O=100W$	10			dB
η	Drain efficiency $V_{DS}=28V$ $I_{DQ}=3.2A$	40			%
VSWR	Load mismatch tolerance $f=1GHz$	10:1			
<u>PER SIDE</u>					
C_{iss}	Input capacitance $V_{DS}=0V$ $V_{GS}=-5V$ $f=1MHz$			200	pF
C_{oss}	Output capacitance $V_{DS}=28V$ $V_{GS}=0$ $f=1MHz$			80	pF
C_{rss}	Reverse transfer capacitance $V_{DS}=28V$ $V_{GS}=0$ $f=1MHz$			6	pF

DIMENSIONS



DM	Millimeter	TOL	Inches	TOL
A	19.05	.50	.750	.020
B	10.8	.13	.425	.005
C	45°	.05	45°	5°
D	9.78	.13	.385	.005
E	5.71	.13	.225	.005
F	27.94	.13	1.100	.005
G	1.52R	.13	.060R	.005
H	10.16	.13	.400	.005
I	22.22	MAX	.875	MAX
J	0.13	.02	.005	.001
K	2.72	.13	.107	.005
M	1.65	.13	.065	.005
N	5.08	.50	.200	.020
O	34.04	.13	1.340	.005
P	1.57R	.08	.062R	.003

HAZARDOUS MATERIAL WARNING

The ceramic portion of the device between leads and metal flange is beryllium oxide. Beryllium oxide dust is highly toxic and care must be taken during handling and mounting to avoid damage to this area. THESE DEVICES MUST NEVER BE THROWN AWAY WITH GENERAL INDUSTRIAL OR DOMESTIC WASTE.

U.S. PATENTS 5,121,176 & 5,179,032
GLOBAL PATENTS PENDING

*C203

*PSPICE MODEL FOR POINT NINE RF N-CHANNEL VERTICAL DMOS POWER FET

*May 2004

```
*          _____GATE
*          I   _____DRAIN
*          I   I   _____SOURCE
*          I   I   I
.SUBCKT C203  10  20  30
*Cin1,Cin2 & Lin model the input side of the package
Cin1  10  30  0.79p
Lin   10  11  0.38n
Cin2  11  30  0.79p

LG    11  12  0.4n      ;Gate bond wire inductance
CGS   12  13  169.6p    ;Gate-source capacitance
MOS   14  12  13      13  C203 L=0.9U W=0.1744      ;D G S B LEVEL1
JFET  16  13  14      C203                          ;D G S
DBODY 13  16  C203                          ;P N
LS    13  30  0.15n    ;Source bond wire inductance
CGD   12  16  4.8p     ;Gate-drain feedback capacitance

*Cout1,Cout2 & Lout model the output side of the package
Cout1 16  30  1.38p
Lout   16  20  0.73n
Cout2  20  30  1.15p

.MODEL C203  NMOS (VTO=3.52 KP=7.77E-4 LAMBDA=0.0224 RD=0.04 RS=0.17)
.MODEL C203  NJF  (VTO=-5.8 BETA=0.5856 LAMBDA=1.357)
.MODEL C203  D    (CJO=240P RS=0.25 VJ=0.7 M=0.33 BV=70)

.ENDS
```